

L Number	Hits	Search Text	DB	Time stamp
1	26090	water with (condensor or trap)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 13:47
2	2623	((water with (condensor or trap)) and ((water with (trap or accumulat\$3 or remov\$3 or collect\$3)) same (mov\$4 or rotat\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 13:49
3	1841	((water with (condensor or trap)) same ((water with (trap or accumulat\$3 or remov\$3 or collect\$3)) same (mov\$4 or rotat\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 13:49
4	202	((water with (condensor or trap)) same ((water with (trap or accumulat\$3 or remov\$3 or collect\$3)) same ((mov\$4 or rotat\$4) with surface)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 13:50
5	19	((water with (condensor or trap)) same ((water with (trap or accumulat\$3 or remov\$3 or collect\$3)) same ((mov\$4 or rotat\$4) with surface))) and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 14:03
6	18	((((water with (condensor or trap)) same ((water with (trap or accumulat\$3 or remov\$3 or collect\$3)) same ((mov\$4 or rotat\$4) with surface))) and (semiconductor or wafer)) and (@ad<20020507 or @rlad<20020507))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 15:48
7	916	((cold or cool\$3 or water) with trap with (mov\$4 or rotat\$4)) and (@ad<20020507 or @rlad<20020507)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 16:32
8	50	((((cold or cool\$3 or water) with trap with (mov\$4 or rotat\$4)) and (@ad<20020507 or @rlad<20020507)) and (semiconductor or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 14:03
9	11	"3719070" "3894741" "4268329" "4831875" "4835974" "5515734" "5758882" "6149130" "6158226" "6244099" "6334928").PN.	USPAT	2004/09/09 14:11
16	2659	remov\$3 with water with surface with (rotat\$3 or mov\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 16:43
17	310	(remov\$3 with water with surface with (rotat\$3 or mov\$3)) and (@ad<20020507 or @rlad<20020507) and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 15:51
18	149	remov\$3 with water with surface with (rotat\$3 or mov\$3) with drum	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 15:53
19	1	(remov\$3 with water with surface with (rotat\$3 or mov\$3) with drum) and (@ad<20020507 or @rlad<20020507) and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 15:51
20	136	(remov\$3 with water with surface with (rotat\$3 or mov\$3) with drum) and (@ad<20020507 or @rlad<20020507)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 15:54
21	41	remov\$3 with water with chamber with (rotat\$3 or mov\$3) with drum	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 15:53
22	34	(remov\$3 with water with chamber with (rotat\$3 or mov\$3) with drum) and (@ad<20020507 or @rlad<20020507)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 15:58

23	905	remov\$3 with water with (cold or cool\$3) with (rotat\$3 or mov\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 15:57
24	99	(remov\$3 with water with (cold or cool\$3) with (rotat\$3 or mov\$3)) same (interior or exterior or internal or external)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 15:58
25	96	((remov\$3 with water with (cold or cool\$3) with (rotat\$3 or mov\$3)) same (interior or exterior or internal or external)) and (@ad<20020507 or @rlad<20020507)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 16:28
26	115	rotating with water with trap	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 16:28
27	91	(rotating with water with trap) and (@ad<20020507 or @rlad<20020507)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 16:43
28	1	((rotating with water with trap) and (@ad<20020507 or @rlad<20020507)) and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 16:29
29	127	(condensat\$3 with trap with (mov\$4 or rotat\$4)) and (@ad<20020507 or @rlad<20020507)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 16:32
30	102990	"127" and (cold or cool\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 16:33
31	59	((condensat\$3 with trap with (mov\$4 or rotat\$4)) and (@ad<20020507 or @rlad<20020507)) and (cold or cool\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 16:33
32	210	remov\$3 with water with surface with (rotat\$3 or mov\$3) with (cold or cool\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 16:43
33	2	(remov\$3 with water with surface with (rotat\$3 or mov\$3) with (cold or cool\$3)) and (@ad<20020507 or @rlad<20020507)) and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 16:45
34	23	(remov\$3 with water with surface with (rotat\$3 or mov\$3) with (cold or cool\$3)) and (@ad<20020507 or @rlad<20020507)) and ((dew adj point) or condensat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 16:46
-	2	6630411.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/09 13:46
-	0	6630411.URPN.	USPAT	2004/09/09 11:47
-	3	("4724677" "5009073" "6461675").PN.	USPAT	2004/09/09 11:49